High Speed Infrared Emitting Diodes, 850 nm, Surface Emitter Technology

VSMY2850RG

VSMY2850G

DESCRIPTION

As part of the SurfLight™ portfolio, the VSMY2850 series are infrared, 850 nm emitting diodes based on GaAlAs surface emitter chip technology with extreme high radiant intensities, high optical power and high speed, molded in clear, untinted plastic packages (with lens) for surface mounting (SMD).

APPLICATIONS

- Miniature light barrier
- Photointerrupters
- Optical switch
- Emitter source for proximity sensors
- IR illumination

FEATURES

- Package type: surface-mount
- Package form: GW, RGW
- Dimensions (L x W x H in mm): 2.3 x 2.3 x 2.8
- Peak wavelength: λ_p = 850 nm
- High reliability
- High radiant power
- Very high radiant intensity
- Angle of half intensity: φ = ± 10°
- Suitable for high pulse current operation
- Terminal configurations: gullwing or reverse gullwing
- Package matches with detector VEMD2500X01 series
- Floor life: 4 weeks, MSL 2a, according to J-STD-020
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Pb-free

e3

RoHS COMPLIANT

HALOGEN FREE

GREEN (5-2008)

PRODUCT SUMMARY				
COMPONENT	I_e (mW/sr)	φ (deg)	λ_P (nm)	t_r (ns)
VSMY2850RG	125	± 10	850	10
VSMY2850G	125	± 10	850	10

Note

- Test conditions see table “Basic Characteristics“

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMY2850RG	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Reverse gullwing
VSMY2850G	Tape and reel	MOQ: 6000 pcs, 6000 pcs/reel	Gullwing

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T_{amb} = 25 °C, unless otherwise specified)				
PARAMETER	**TEST CONDITION**	**SYMBOL**	**VALUE**	**UNIT**
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	t_p/T = 0.5, t_p = 100 µs	I_{FM}	200	mA
Surge forward current	t_p = 100 µs	I_{FSM}	1	A
Power dissipation		P_V	190	mW
Junction temperature		T_j	100	°C
Operating temperature range		T_{amb}	-40 to +85	°C
Storage temperature range		T_{stg}	-40 to +100	°C
Soldering temperature	According to Fig. 10, J-STD-020	T_{sd}	260	°C
Thermal resistance junction-to-ambient	EIA / JESD51	R_{thJA}	250	K/W

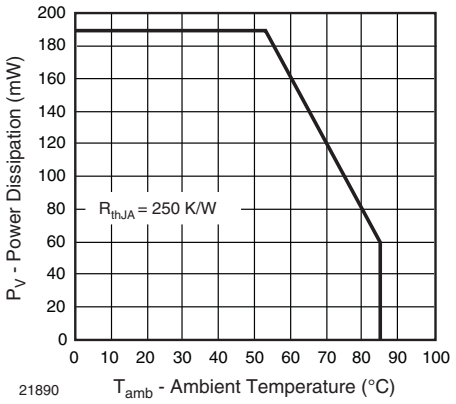


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

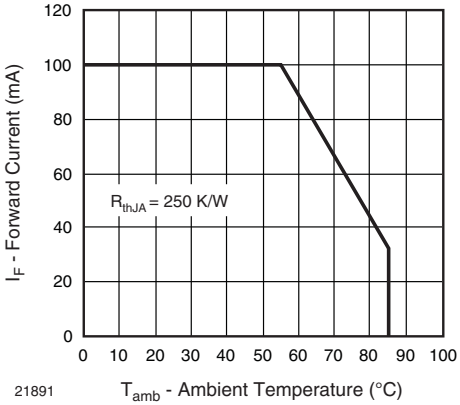


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)						
PARAMETER	**TEST CONDITION**	**SYMBOL**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Forward voltage	I_F = 100 mA, t_p = 20 ms	V_F	-	1.6	1.9	V
	I_F = 1 A, t_p = 100 µs	V_F	-	2.8	-	V
Temperature coefficient of V_F	I_F = 100 mA	TK_{VF}	-	-1.5	-	mV/K
Reverse current		I_R	Not designed for reverse operation			µA
Junction capacitance	V_R = 0 V, f = 1 MHz, E = 0 mW/cm²	C_J	-	50	-	pF
Radiant intensity	I_F = 100 mA, t_p = 20 ms	I_e	70	125	210	mW/sr
	I_F = 1 A, t_p = 100 µs	I_e	-	1000	-	mW/sr
Radiant power	I_F = 100 mA, t_p = 20 ms	ϕ_e	-	55	-	mW
Temperature coefficient of radiant power	I_F = 100 mA	$TK\phi_e$	-	-0.12	-	%/K
Angle of half intensity		φ	-	± 10	-	deg
Peak wavelength	I_F = 100 mA	λ_p	840	850	870	nm
Spectral bandwidth	I_F = 30 mA	$\Delta\lambda$	-	30	-	nm
Temperature coefficient of λ_p	I_F = 30 mA	$TK\lambda_p$	-	0.25	-	nm/K
Rise time	I_F = 100 mA, 10 % to 90 %	t_r	-	10	-	ns
Fall time	I_F = 100 mA, 10 % to 90 %	t_f	-	10	-	ns

BASIC CHARACTERISTICS (T_{amb} = 25 °C, unless otherwise specified)

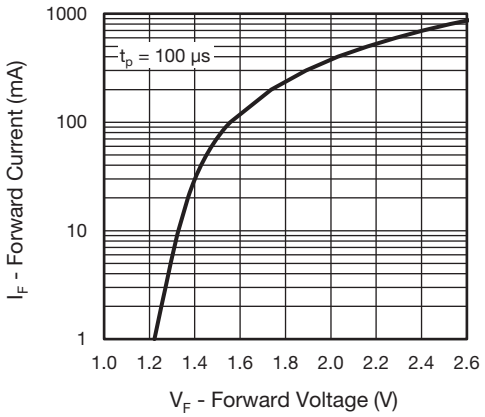


Fig. 3 - Forward Current vs. Forward Voltage

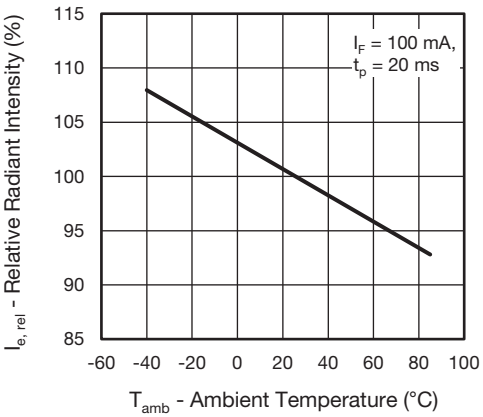


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

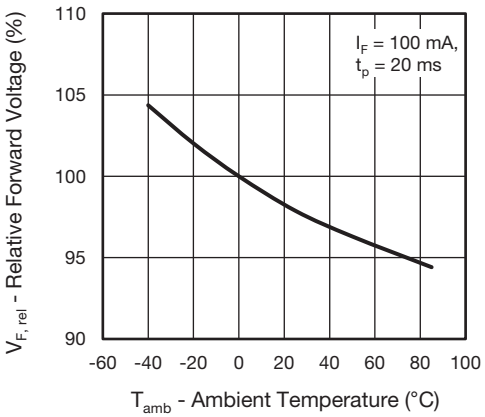


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

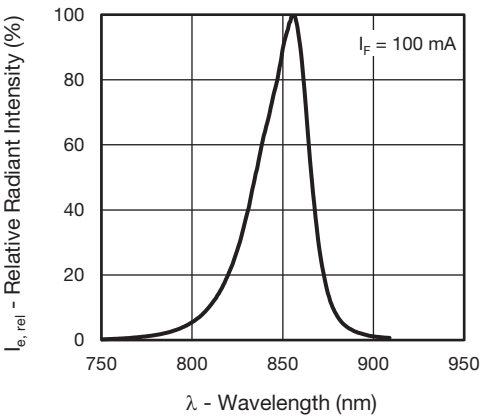


Fig. 7 - Relative Radiant Intensity vs. Wavelength

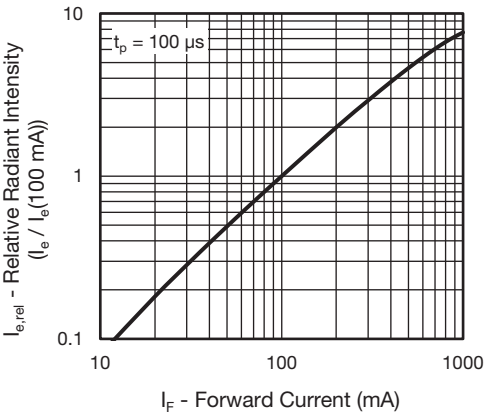


Fig. 5 - Relative Radiant Intensity vs. Forward Current

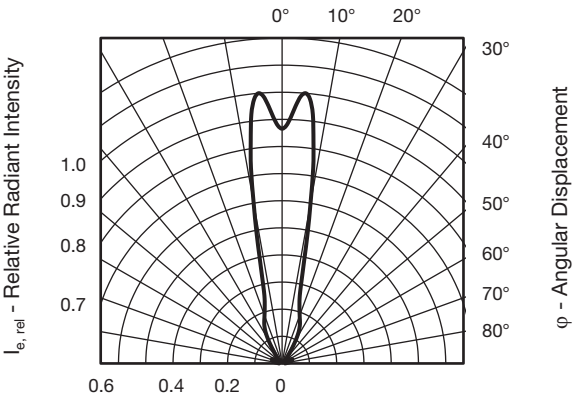


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

SOLDER PROFILE

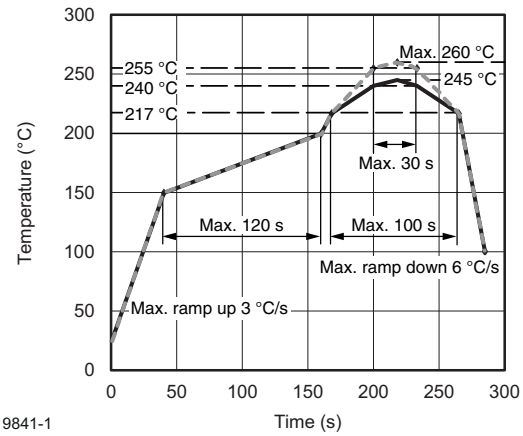


Fig. 9 - Lead (Pb)-free Reflow Solder Profile
According to J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

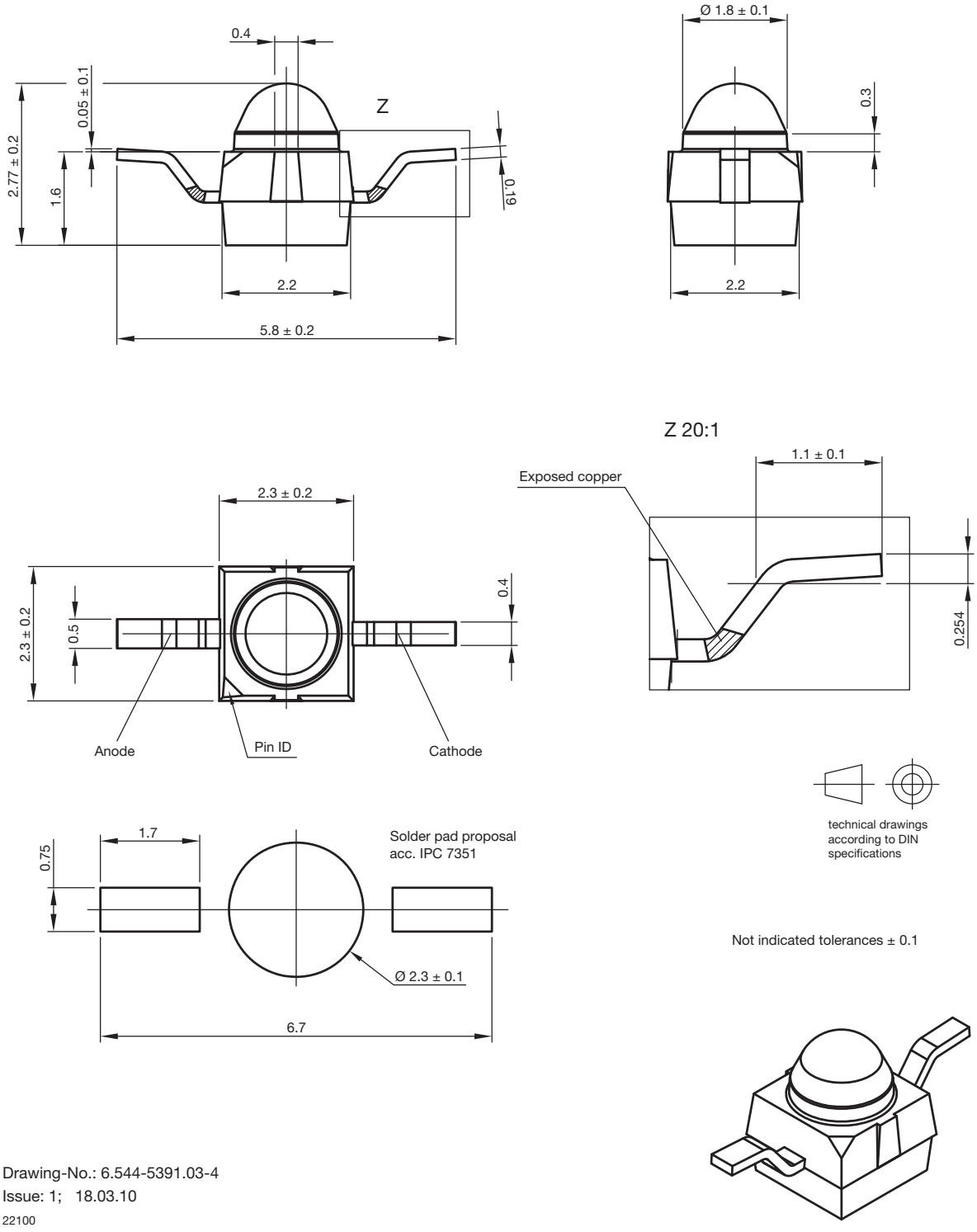
Conditions: T_{amb} < 30 °C, RH < 60 %

Moisture sensitivity level 2a, according to J-STD-020.

DRYING

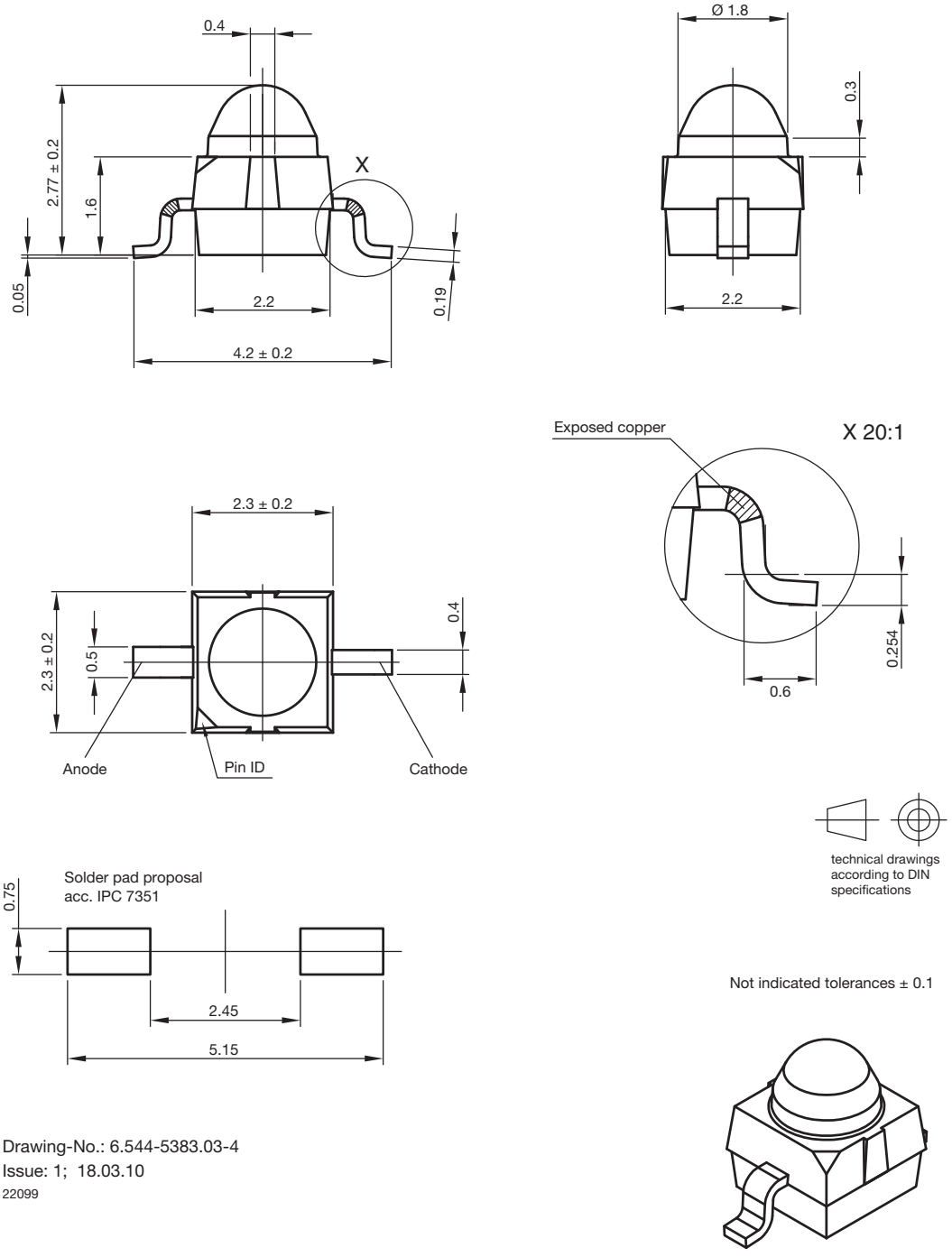
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at 40 °C (+ 5 °C), RH < 5 %.

PACKAGE DIMENISONS in millimeters: **VSMY2850RG**



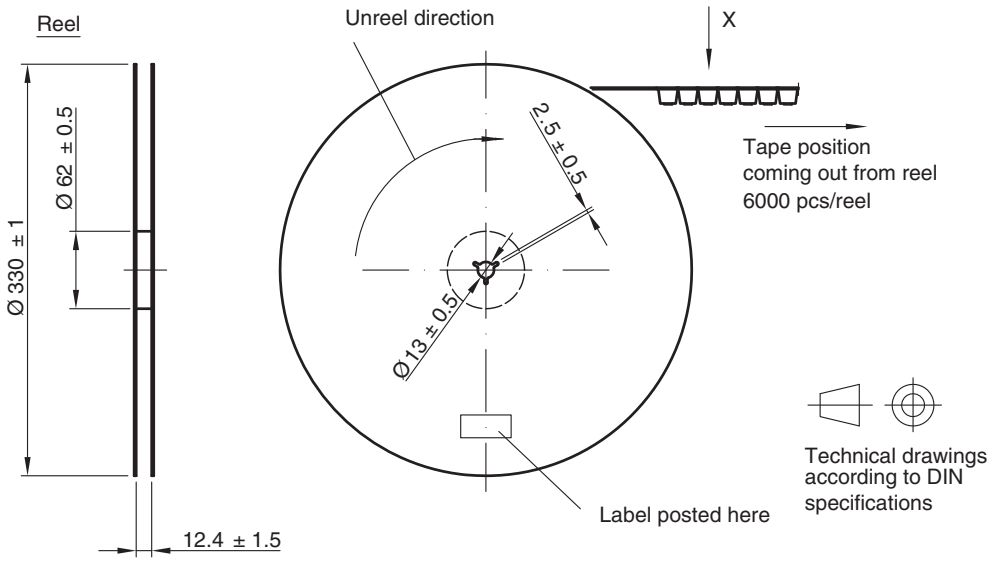
Drawing-No.: 6.544-5391.03-4
Issue: 1; 18.03.10
22100

PACKAGE DIMENSIONS in millimeters: **VSMY2850G**

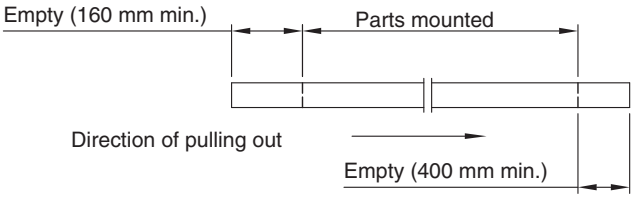


Drawing-No.: 6.544-5383.03-4
Issue: 1; 18.03.10
22099

TAPING AND REEL DIMENSIONS in millimeters: **VSMY2850RG**

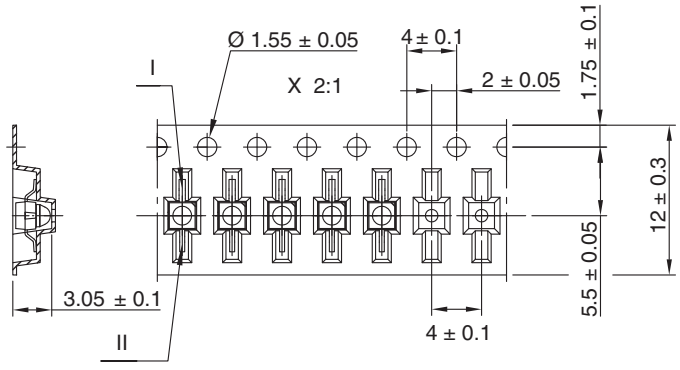


Leader and trailer tape:



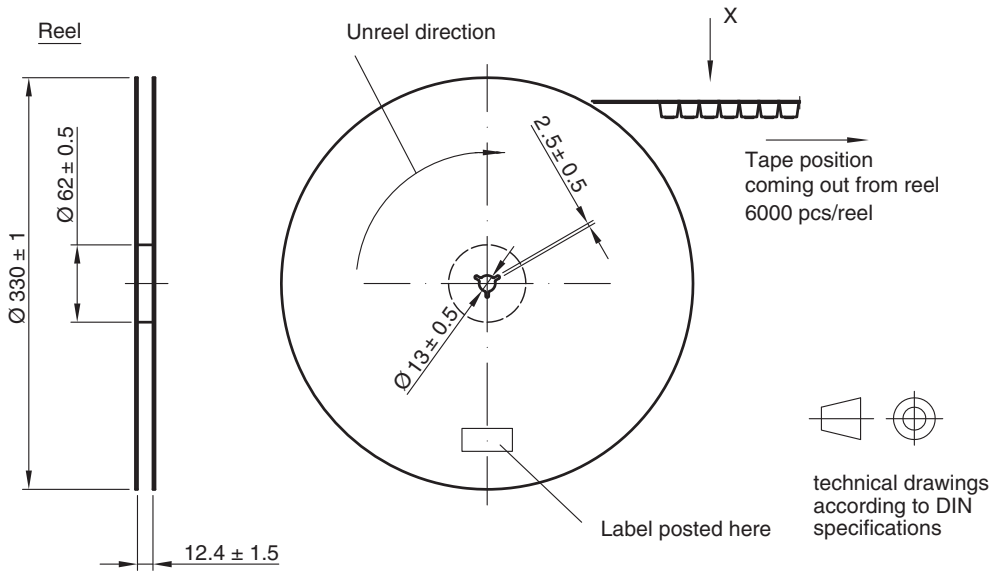
Terminal position in tape

Device	Lead I	Lead II
VEMT2000	Collector	Emitter
VEMT2500		
VEMD2000	Cathode	Anode
VEMD2500		
VSMB2000		
VSMG2000		
VSMY2850RG	Anode	Cathode

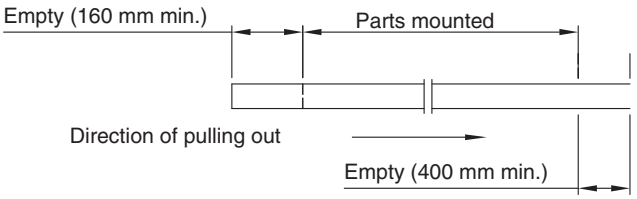


Drawing-No.: 9.800-5100.01-4
Issue: 2; 18.03.10
21572

TAPING AND REEL DIMENSIONS in millimeters: **VSMY2850G**

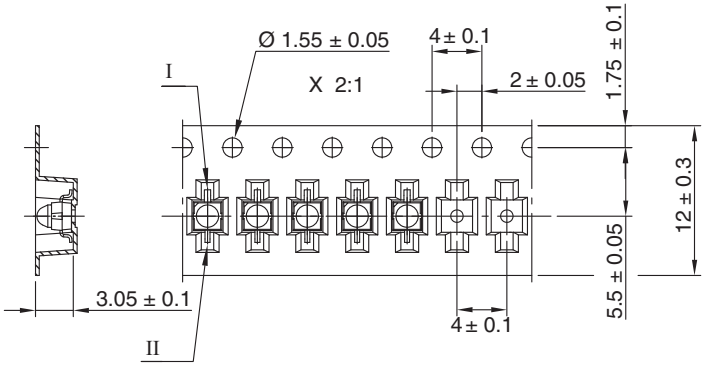


Leader and trailer tape:



Terminal position in tape

Device	Lead I	Lead II
VEMT2020	Collector	Emitter
VEMT2520		
VSMB2020	Cathode	Anode
VSMG2020		
VEMD2020		
VEMD2520		
VSMY2850G	Anode	Cathode



Drawing-No.: 9.800-5091.01-4
Issue: 3; 18.03.10

21571

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